

TPS31&TPS32

Lightweight Two-Part Thermal Conductive Sealing Glue

LiPOLY's TPS31/TPS32 is a low-density, two-part compound silicone base thermal conductive sealing material. It's low viscosity and excellent fluidity can tightly fill the gaps of electrical components and cover the tolerances between components. It has excellent thermal conductivity, low density and insulation properties.

■ FEATURES

- / Lightweight, Low Density, Thermal Conductivity 0.55 & 1.5 W/m*K
- / Medium-to-high hardness silicone material with excellent insulation and weather resistance
- / Suitable for automatic dispensing machine
- / TPS31 Moisture absorb hardening reaction at room temperature.
- / TPS32 Hardened at room temperature, also can be heated to accelerate the hardening reaction.

■ TYPICAL APPLICATION

- / Heat Dissipation & lightweight applications, such as Automotive electronic devices, Mobile communication device, Drone & aircraft, Sports and leisure electronic products, Portable game consoles, VR devices and etc.

■ PRESERVATION

- / It can be preserved for 24 months under the condition of unopened and under room temperature 25°C.

■ TYPICAL PROPERTIES

PROPERTY	TPS31	TPS32	TEST METHOD	UNIT
Color	White (A part) Translucent (B part)	White(A part) Black(B part)	Visual	-
Resin Base	Silicone	Silicone	-	-
A:B	100:10	100:100	-	-
Viscosity	1.9	3.2	ISO 3219	Pa.s
Density	1.35	1.72	ASTM D792	g/cm ³
Application temperature	-60~180	-60~180	-	°C
Working Time	25°C/30 min	25°C/1 hrs	By LiPOLY	-
Curing Condition 2	25°C/48 hrs	80°C/1 hrs	By LiPOLY	-
Curing Condition 3	-	25°C/24 hrs	By LiPOLY	-
Hardness	55	65	ASTM D2240	Shore A
Shelf Life	24 months	24 months	-	-
ROHS & REACH	Compliant	Compliant	-	-
ELECTRICAL				
Dielectric breakdown	10	9	ASTM D149	KV/mm
Volume resistivity	>10 ¹³	>10 ¹³	ASTM D257	Ohm-m
THERMAL				
Thermal conductivity	0.55	1.5	ASTM D5470	W/m*K

